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January 2016

FDBL0110N60

N-Channel PowerTrench[®] MOSFET 60 V, 300 A, 1.1 m Ω

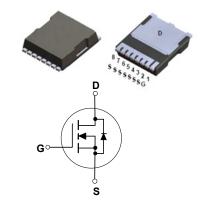
Features

- Typical $R_{DS(on)}$ = 0.85 m Ω at V_{GS} = 10V, I_D = 80 A
- Typical $Q_{g(tot)}$ = 170 nC at V_{GS} = 10V, I_D = 80 A
- UIS Capability
- RoHS Compliant

Applications

- Industrial Motor Drive
- Industrial Power Supply
- Industrial Automation
- Battery Operated tools
- Battery Protection
- Solar Inverters
- UPS and Energy Inverters
- Energy Storage
- Load Switch





For current package drawing, please refer to the Fairchild website at https://www.fairchildsemi.com/evaluate/package-specifications/packageDetails.ht-ml?id=PN PSOFA-008

MOSFET Maximum Ratings $T_J = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter		Ratings	Units	
V_{DSS}	Drain-to-Source Voltage		60	V	
V_{GS}	Gate-to-Source Voltage		±20	V	
	Drain Current - Continuous (V _{GS} =10) (Note 1)	T _C = 25°C	300	^	
ID	Pulsed Drain Current	T _C = 25°C	See Figure 4	A	
E _{AS}	Single Pulse Avalanche Energy	(Note 2)	1167	mJ	
D	Power Dissipation		429	W	
P_D	Derate Above 25°C		2.86	W/°C	
T _J , T _{STG}	Operating and Storage Temperature		-55 to + 175	°C	
$R_{\theta JC}$	Thermal Resistance, Junction to Case		0.35	°C/W	
$R_{\theta JA}$	Maximum Thermal Resistance, Junction to Ambient	(Note 3)	43	°C/W	

Notes:

- 1: Current is limited by bondwire configuration.
- 2: Starting T_{.J} = 25°C, L = 0.57mH, I_{AS} = 64A, V_{DD} = 40V during inductor charging and V_{DD} = 0V during time in avalanche.
- 3: R_{0,JA} is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{0,JC} is guaranteed by design, while R_{0,JA} is determined by the board design. The maximum rating presented here is based on mounting on a 1 in² pad of 2oz copper.

Package Marking and Ordering Information

Device Marking	Device	Package			
FDBL0110N60	FDBL0110N60	MO-299A	-	-	-

Units

Max.

Electrical Characteristics $T_J = 25$ °C unless otherwise noted.

Parameter

Off Characteristics							
B_{VDSS}	Drain-to-Source Breakdown Voltage	$I_D = 250 \mu A$	V _{GS} = 0V	60	-	-	V
I _{DSS}	Drain-to-Source Leakage Current	$V_{DS} = 60V$	$T_{J} = 25^{\circ}C$	-	-	1	μΑ
		$V_{GS} = 0V$	$T_J = 175^{\circ}C \text{ (Note 4)}$	-	-	1	mA
I_{GSS}	Gate-to-Source Leakage Current	$V_{GS} = \pm 20V$		-	-	±100	nA

Test Conditions

Min.

Тур.

On Characteristics

Symbol

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$		2.0	3.0	4.0	V
R _{DS(on)}	Drain to Source On Resistance	I _D = 80A,	$T_{\rm J} = 25^{\rm o}{\rm C}$	-	0.85	1.1	mΩ
		V _{GS} = 10V	$T_J = 175^{\circ}C \text{ (Note 4)}$	-	1.5	2.2	mΩ

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{DS} = 30V, V _{GS} = 0V, f = 1MHz		-	13650	-	pF
C _{oss}	Output Capacitance			-	3375	-	pF
C _{rss}	Reverse Transfer Capacitance	- 1 - 11VII 12	I - IIVIIIZ		255	-	pF
R_g	Gate Resistance	f = 1MHz		-	2.3	-	Ω
$Q_{g(ToT)}$	Total Gate Charge at 10V	V _{GS} = 0 to 10V	V _{DD} = 48V	-	170	220	nC
$Q_{g(th)}$	Threshold Gate Charge	$V_{GS} = 0 \text{ to } 2V$	I _D = 80A	-	24	32	nC
Q_{gs}	Gate-to-Source Gate Charge		_	-	56	-	nC
Q_{gd}	Gate-to-Drain "Miller" Charge			-	24	-	nC

Switching Characteristics

t _{on}	Turn-On Time	V_{DD} = 30V, I_{D} = 80A, V_{GS} = 10V, R_{GEN} = 6 Ω	-	-	137	ns
t _{d(on)}	Turn-On Delay		-	45	-	ns
t _r	Rise Time		-	61	-	ns
t _{d(off)}	Turn-Off Delay		-	80	-	ns
t _f	Fall Time		-	41	-	ns
t _{off}	Turn-Off Time		ı	ı	156	ns

Drain-Source Diode Characteristics

I_S	Maximum Continuous Drain to Source Diode Forward Current			-	300	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current			-	See Figure 4	Α
V_{SD}	Source-to-Drain Diode Voltage	I _{SD} =80A, V _{GS} = 0V	-	-	1.25	V
	Source-to-Drain Diode Voltage	$I_{SD} = 40A, V_{GS} = 0V$	-	-	1.2	V
t _{rr}	Reverse-Recovery Time	$I_F = 80A$, $dI_{SD}/dt = 100A/\mu s$,	-	107	139	ns
Q_{rr}	Reverse-Recovery Charge	V _{DD} =48V	-	183	265	nC

Note:

4: The maximum value is specified by design at T_J = 175°C. Product is not tested to this condition in production.

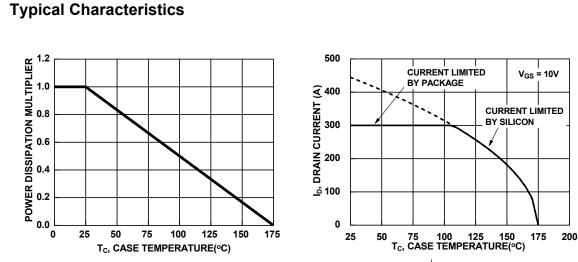
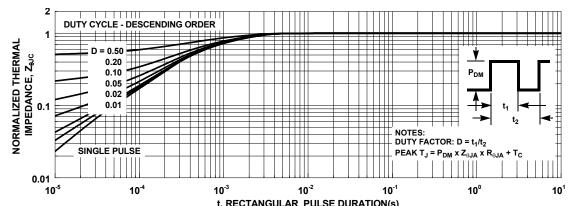


Figure 1. Normalized Power Dissipation vs. Case Temperature

Figure 2. Maximum Continuous Drain Current vs.
Case Temperature



t, RECTANGULAR PULSE DURATION(s)
Figure 3. Normalized Maximum Transient Thermal Impedance

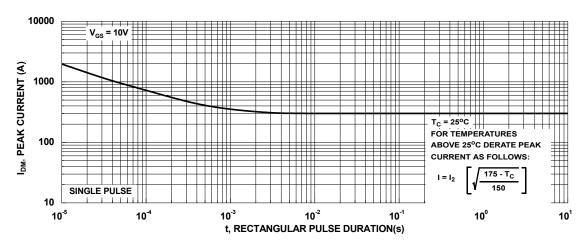


Figure 4. Peak Current Capability

Typical Characteristics

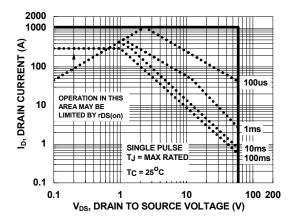
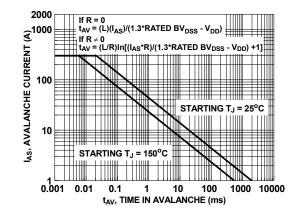


Figure 5. Forward Bias Safe Operating Area



NOTE: Refer to Fairchild Application Notes AN7514 and AN7515

Figure 6. Unclamped Inductive Switching

Capability

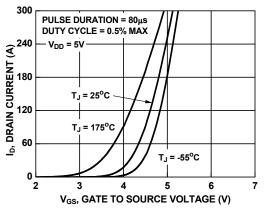


Figure 7. Transfer Characteristics

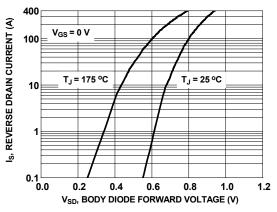


Figure 8. Forward Diode Characteristics

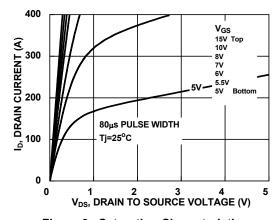


Figure 9. Saturation Characteristics

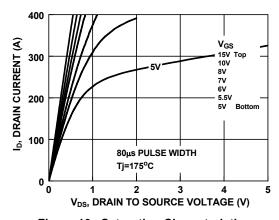
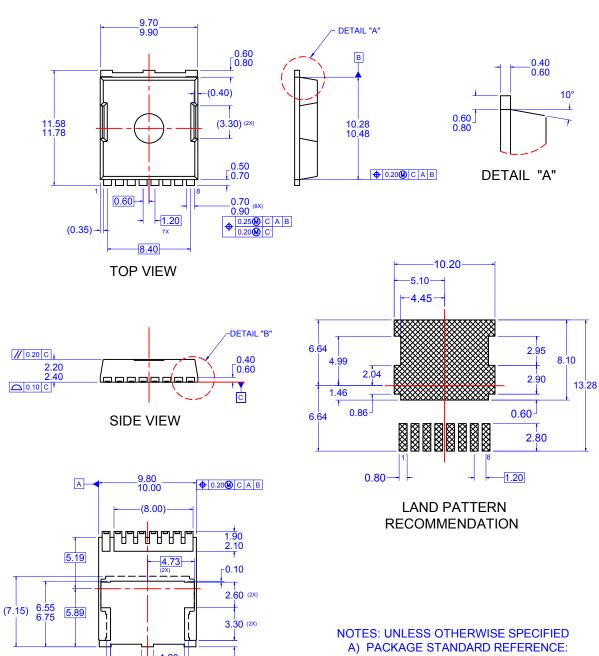


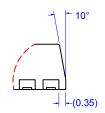
Figure 10. Saturation Characteristics



- JEDEC MO-299, ISSUE A, DATED NOVEMBER
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
- D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- E) DRAWING FILE NAME: MKT-PSOF08AREV3

- - 1.20 0.65-3.75 7.60 -(8.30)

BOTTOM VIEW



DETAIL "B"

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